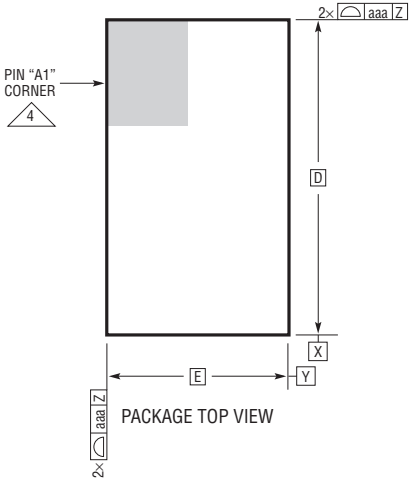
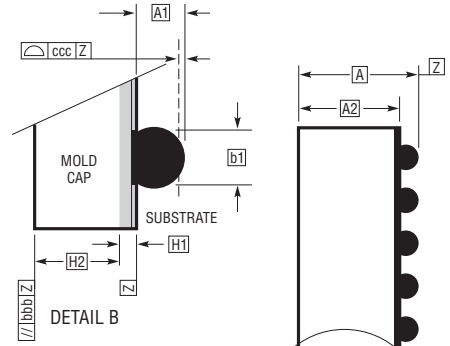
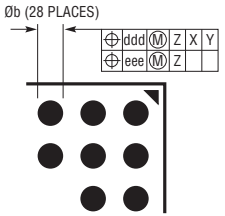
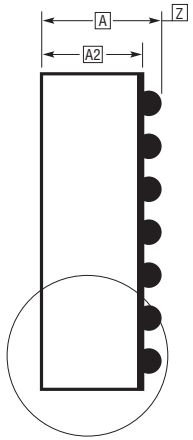
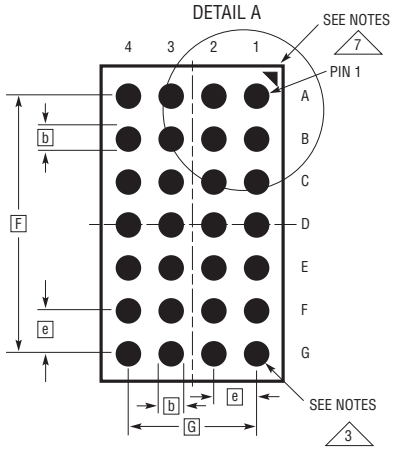
BGA Package
28-Lead (6.25mm × 4mm × 2.22mm)
(Reference LTC DWG # 05-08-1517 Rev Ø)

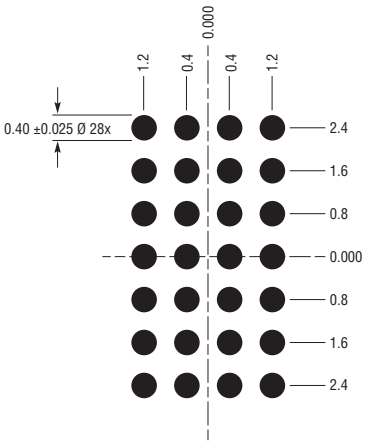






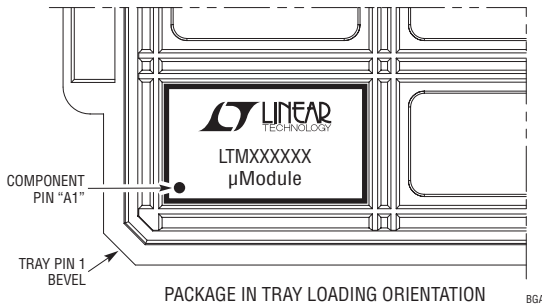






DIMENSIONS				
SYMBOL	**MIN**	**NOM**	**MAX**	**NOTES**
A	2.02	2.22	2.42	
A1	0.30	0.40	0.50	
A2	1.72	1.82	1.92	
b	0.45	0.50	0.55	
b1	0.37	0.40	0.43	
D		6.25		
E		4.00		
e		0.80		
F		4.80		
G		2.40		
H1	0.27	0.32	0.37	
H2	1.45	1.50	1.55	
aaa			0.15	
bbb			0.10	
ccc			0.20	
ddd			0.15	
eee			0.08	
TOTAL NUMBER OF BALLS: 28				

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
2. ALL DIMENSIONS ARE IN MILLIMETERS
3. BALL DESIGNATION PER JEP95
4. DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
5. PRIMARY DATUM -Z- IS SEATING PLANE
6. SOLDER BALL COMPOSITION IS 96.5% Sn/3.0% Ag/0.5% Cu
7. PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG µModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY



BGA 28 0915 REV Ø